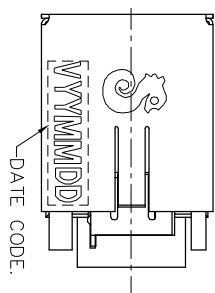
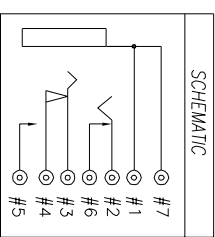


RECOMMENDED PCB LAYOUT (TOP VIEW)
(TOLERANCE: ±0.05)



1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
2. CONTACT RESISTANCE: 30mΩ MAX.
3. INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
6. INSERTION FORCE: 0.4 - 3Kg.
7. WITHDRAWAL FORCE: 0.3 - 2Kg.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
10. MARKING: MARK "S" ON TOP OF CONNECTOR.
11. PACKAGING: TAPE & REEL.
12. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
13. GREEN PRODUCT IDENTIFICATION MARK ON JACK:
14. GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING:
15. FOR LEAD-FREE WAVE SOLDERING PROCESS.
16. DATE CODE: WYMMDD

H	SHIELDING	1	PHOSPHOR BRONZE 0.21	N: 60u" Min.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.21	60D FLASH ON CONTACT AREA
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.21	5x 120u" ON SOLDER; ALL OVER IN 50u"
E	RING SPRING	1	PHOSPHOR BRONZE 0.21	BRASS 0.25t
D	SHUNT TERMINAL-A	1	PHOSPHOR BRONZE 0.25t	4g 20u" Min OVER N: 60u" Min.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	
B	EARTH	1	COPPER ALLOY 0.3t	
A	BODY	1	HIGH TEMP-THERMOPLASTIC (UL 94V-0)	GREEN (PAVTONO NO.3415G)
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS: ANGLES:				
X	:±0.5	X	:±2°	
XX	:±0.3	XX	:±1°	
XXX	:±0.2			

Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
TITLE	3.50 PHONE JACK
DWN	JIE-FU PART NO. 2SJ-S351-013
CHKD	CERRY SCALE: 4/1 UNIT: mm
APVD	LUSSEN SIZE: A3 SHEET: 1 OF 1 REV: F

CUSTOMER COPY

REV	ECN NO OR DESCRIPTION	REVISED	DATE
D	ECN: S080116	Mcky	2008.01.23
E	ECN NO: S110320	Cerry	2011.03.28
F	ECN NO: S161121-R	JIE-FU	2017.02.20